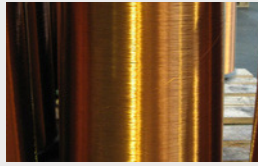


## SELF BONDABLE ROUND COPPER



SOLDERABLE AND BONDABLE COPPER	S.H.180 TERMO	S.H.180 TERMO
Thermal class	180°C	180°C
Nature of the isolation	<b>Base Coat:</b> Polyurethane <b>Top Coat:</b> Modified Butyral	<b>Base Coat:</b> Polyurethane <b>Top Coat:</b> Alyphatic Polyamide
Diameter	Φ 0.15 - 2.00mm	Φ 0.15 - 2.00mm
Grade	G-1B and G-2B	G-1B and G-2B
Colour	Natural	Natural
Bonding temperature	140°C	170°C
Resoftening temperature	120°C	155°C
Breakdown voltage	≥ 1.5 x IEC	≥ 1.5 x IEC
Heat shock	> 175°C	> 175°C
Solderability	470°C 4 sec	470°C 4 sec
Cut through	≥ 250	≥ 250
Chemical resistance	Good	Good
Standard	IEC-851 (Testing methods)	IEC-851 (Testing methods)
Certifications	ISO TS 16949 ISO 9001:2000	ISO TS 16949 ISO 9001:2000
Description	Cu S.H.180 "Diameter" G-"Grade"	Cu S.H.180 "Diameter" G-"Grade"
Applications	Stators and rotors of micro-motors, loudspeakers, TV deflecting yokes.	Stators and rotors of micro-motors, loudspeakers, TV deflecting yokes.